

BGI100

Automatic hotmelt lamination equipment

Product description

The BGI100 is an automatic equipment for lamination of hotmelt tape on reels of chips (dimension 35mm width).

Advantages

- used for memory, microprocessor chips...
- throughput of 5000 units per hour
- compact and easy to use
- screen touch interface
- adjustment of time, pressure, temperature...



Card manufacturing equipments

- option BGI100a : punch of glue tape. This option allows to punch the glue tape in order to reduce deformation behind the card during the implanting of the chip.

Technical specifications

DIMENSIONS			
Length	Width	Height	Weight
1500 mm	560 mm	1700 mm	95 kg
TEMPERATURE			
Operating		Storage	
+5°C to +50°C		-20°C to +60°C	
ELECTRICAL CHARACTERISTICS			
Power : 100-240V AC ; Frequency : 50-60Hz single phase ; Intensity : 3,15A			
PNEUMATIC CHARACTERISTICS			
6 bars			
IN CONFORMITY WITH CE DIRECTIVES			

Markets

Microprocessor and memory chips for Banking, GSM, Telecom, e-ID, health, prepaid, gift, loyalty cards ...

Ordering information

Description	Reference number
Automatic hotmelt lamination equipment	BGI100
Option punch of glue tape	BGI100a